

INTERNATIONAL STANDARD



BASIC EMC PUBLICATION

**Electromagnetic compatibility (EMC) –
Part 4-36: Testing and measurement techniques – IEMI immunity test methods
for equipment and systems**



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INTERNATIONAL ELECTROTECHNICAL COMMISSION

ELECTROMAGNETIC COMPATIBILITY (EMC) –

**Part 4-36: Testing and measurement techniques –
 IEMI immunity test methods for equipment and systems**

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Full information on the voting for the approval of this standard can be found in the report on voting indicated in the above table.

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